

REMARKS

I. Status of Claims

Claims 1-24 are pending in the application. Claims 1-7, 11-13, 15, 16, 18, 19 and 21-24 are withdrawn from consideration. Claims 8-10, 14, 17 and 20 are rejected.

Claims 1, 2, 5 and 8 are amended to recite in Markush form the structures that have a polymerization initiating ability in Formula (IV), with support in the specification, for example, at page 9, lines 7-12 and page 15, lines 1-7.

No new matter is added. Accordingly, entry of the Amendment is respectfully requested.

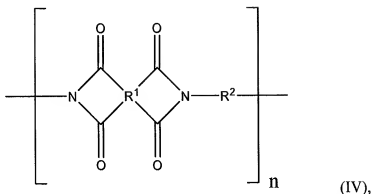
II. Response to Rejection of Claims Under 35 U.S.C. § 103

Claims 8-10, 14, 17 and 20 are rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over “*Improved Adhesion Between Kapton Film and Copper Metal By Plasma Graft Polymerization of Vinylimidazole*” by Inagaki et al. (*Macromolecules*, 1996, **29**, 1642-1648; hereafter “Inagaki”).

Applicants respectfully submit that claims 8-10, 14, 17 and 20 are patentable over Inagaki, at least for the following reasons.

Amended claim 8 recites:

A method for forming a conductive film, comprising the processes of:
applying energy to the surface of a substrate containing polyimide
represented by general formula (IV):



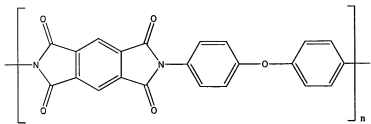
wherein R^1 represents a tetravalent organic group, R^2 represents a divalent organic group, n represents an integer of 1 or more, and at least one of R^1 and R^2 is a group containing a structure having a polymerization initiating ability, wherein the structure having a polymerization initiating ability is selected from the group consisting of an aromatic ketone, an onium salt compound, an organic peroxide, a thio compound, a hexaaryl biimidazole compound, a ketoxime ester compound, a borate compound, an adinium compound, an active ester compound, a compound having a carbon halogen bond, and a pyridinium compound, to generate active points on the surface of the substrate; and to generate a graft polymer that is directly bonded to the surface of the substrate starting from the active points and that has a functional group interacting with an electroless plating catalyst or the precursor thereof;

applying the electroless plating catalyst or the precursor thereof to the graft polymer; and

carrying out electroless plating. (emphasis added.)

Inagaki is discussed at page 2, lines 14-22 of the present specification. The DuPont Kapton polyimide film disclosed in Inagaki does not have a structure having a polymerization

initiating ability. For example, Kapton has a general formula:



In the above formula representing the polyimide of Inagaki, neither of the groups corresponding to R¹ and R² of present Formula (IV) is selected from the recited group consisting of an aromatic ketone, an onium salt compound, an organic peroxide, a thio compound, a hexaaryl biimidazole compound, a ketooxime ester compound, a borate compound, an adinium compound, an active ester compound, a compound having a carbon halogen bond, and a pyridinium compound, as recited in amended claim 1. Therefore, Inagaki does not disclose the polyimide of the present invention. Nor is there any suggestion or motivation to modify the polyimide of Inagaki to arrive at the presently claimed compound.

Moreover, by employing the polyimide film of amended claim 1, the present invention provides a conductive film having excellent adhesiveness and a low surface resistance, as shown in the working Examples of the present specification.

In view of the above, Applicants submit that claim 8 is patentable over Inagaki. Claims 9, 10, 14, 17 and 20 are also patentable, at least by virtue of their dependence from claim 8. Accordingly, reconsideration and withdrawal of the § 103 rejection of the claims are respectfully requested.

III. Request for Rejoinder

Applicants respectfully request rejoinder of withdrawn claims 1-7, 11-13, 15-16 and 18-19. Claims 1-7, 11-13, 15-16 and 18-19 were originally withdrawn due to Applicants' election of Group III, claims 8-10, 14, 17 and 20, in a Response to Restriction Requirement filed on March 13, 2008.

Applicants respectfully submit that upon entry of the present Amendment, claims 1-24 will be linked so as to form a single general inventive concept under PCT Rule 13.1.

Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

/Brett S. Sylvester/

Brett S. Sylvester
Registration No. 32,765

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

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